

HiPerFRED

600 V V_{RRM}

15 A I FAV

25 ns

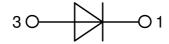
High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DPG30I600PM



Backside: isolated



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-220FP

- Isolation Voltage: 2500 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

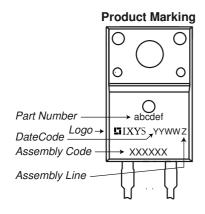
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Fast Diode					Ratings		
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ng voltage	$T_{VJ} = 25^{\circ}C$			600	V
V _{RRM}	max. repetitive reverse blocking vo	oltage	$T_{VJ} = 25^{\circ}C$			600	V
IR	reverse current, drain current	$V_R = 600 \text{ V}$	$T_{VJ} = 25^{\circ}C$			250	μΑ
		$V_R = 600 \text{ V}$	$T_{VJ} = 150$ °C			2	mA
V _F	forward voltage drop	I _F = 30 A	$T_{VJ} = 25^{\circ}C$			2.52	V
		$I_F = 60 \text{ A}$				3.22	٧
		I _F = 30 A	T _{VJ} = 150°C			1.63	V
		$I_F = 60 \text{ A}$				2.27	٧
I FAV	average forward current	T _C = 95°C	T _{vJ} = 175°C			15	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		$T_{VJ} = 175$ °C			0.84	V
\mathbf{r}_{F}	slope resistance	ss calculation only				20	mΩ
R _{thJC}	thermal resistance junction to case	9				3.5	K/W
R _{thCH}	thermal resistance case to heatsin	k			0.50		K/W
P _{tot}	total power dissipation		$T_C = 25^{\circ}C$			165	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			250	Α
CJ	junction capacitance	$V_R = 400 \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		26		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 ^{\circ}\text{C}$		2.5		Α
		$I_F = 30 \text{ A}; V_R = 300 \text{ V}$	$T_{VJ} = 100^{\circ}C$		4.5		Α
t _{rr}	reverse recovery time	$I_F = 30 \text{ A}; V_R = 300 \text{ V}$ -di _F /dt = 200 A/µs	$T_{VJ} = 25 ^{\circ}\text{C}$		25		ns
	J	1	$T_{VJ} = 100^{\circ}C$		70		ns



Package TO-220FP			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal					35	Α
T _{VJ}	virtual junction temperature				-55		175	°C
T _{op}	operation temperature			-55		150	°C	
T _{stg}	storage temperature			-55		150	°C	
Weight						2		g
M _D	mounting torque				0.4		0.6	Nm
F _c	mounting force with clip				20		60	N
d _{Spp/App}	creepage distance on surface striking distance thro		terminal to terminal	3.2	2.7			mm
$d_{Spb/Apb}$	creepage distance on surface s	triking distance through an	terminal to backside 2.5		2.5			mm
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz, RMS; lisoL ≤ 1 mA		2500			V
		t = 1 minute			2100			٧



Part description

D = Diode P = HiPerFRED

G = extreme fast

30 = Current Rating [A]

I = Single Diode

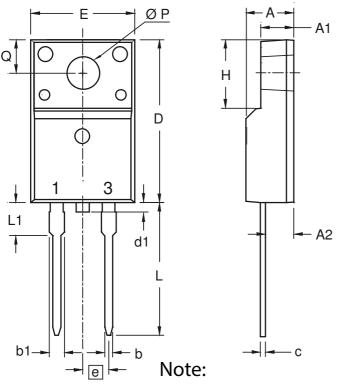
600 = Reverse Voltage [V] PM = TO-220ACFP (2)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DPG30I600PM	DPG30I600PM	Tube	50	521763

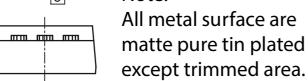
Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 175 ^{\circ}\text{C}$
$I \rightarrow V_0$	R _o -	Fast Diode		
V _{0 max}	threshold voltage	0.84		V
$R_{0 max}$	slope resistance *	17		$m\Omega$



Outlines TO-220FP



Dim.	Millim	neters	Inches		
חווט.	min	max	min	max	
Α	4.50	4.90	0.177	0.193	
A1	2.34	2.74	0.092	0.108	
A2	2.56	2.96	0.101	0.117	
b	0.70	0.90	0.028	0.035	
b1	1.27	1.47	0.050	0.058	
С	0.45	0.60	0.018	0.024	
D	15.67	16.07	0.617	0.633	
d1	0	1.10	0	0.043	
Е	9.96	10.36	0.392	0.408	
е	2.54	2.54 BSC		.100 BSC	
Н	6.48	6.88	0.255	0.271	
L	12.68	13.28	0.499	0.523	
L1	3.03	3.43	0.119	0.135	
ØΡ	3.08	3.28	0.121	0.129	
Q	3.20	3.40	0.126	0.134	







Fast Diode

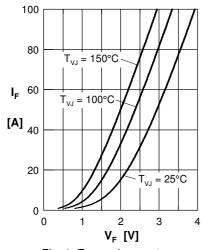


Fig. 1 Forward current I_F versus V_F

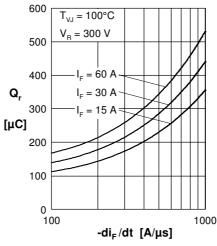


Fig. 2 Typ. reverse recovery charge Q, versus -di_F/dt

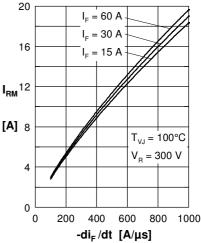


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

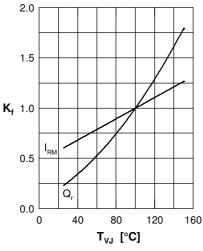


Fig. 4 Dynamic parameters Q_r , I_{RM} versus T_{VJ}

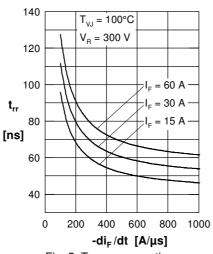


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

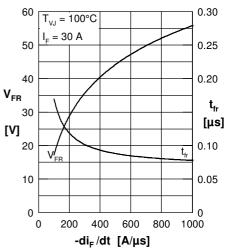


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

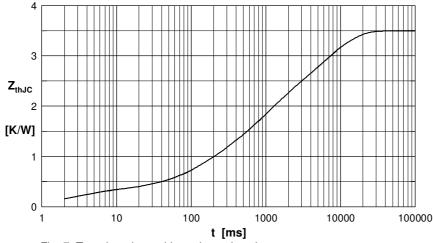


Fig. 7 Transient thermal impedance junction to case

Constants for $Z_{\rm thJC}$ calculation:

i	R_{thi} (K/W)	t _i (s)
1	0.30	0.003
2	0.50	0.130
3	1.15	0.800
4	1.55	6.500